

UNITED STATES PATENT AND TRADEMARK OFFICE

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BEFORE THE PATENT TRIAL AND APPEAL BOARD

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TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.,  
TSMC NORTH AMERICA CORPORATION, FUJITSU  
SEMICONDUCTOR LIMITED, FUJITSU SEMICONDUCTOR  
AMERICA, INC., THE GILLETTE COMPANY, ADVANCED MICRO  
DEVICES, INC., RENESAS ELECTRONICS CORPORATION,  
RENESAS ELECTRONICS AMERICA, INC., GLOBAL FOUNDRIES  
U.S., INC., GLOBALFOUNDRIES DRESDEN MODULE ONE LLC &  
CO. KG, GLOBALFOUNDRIES DRESDEN MODULE TWO LLC & CO.  
KG, TOSHIBA AMERICA ELECTRONIC COMPONENTS, INC.,  
TOSHIBA AMERICA INC., TOSHIBA AMERICA INFORMATION  
SYSTEMS, INC., and TOSHIBA CORPORATION,  
Petitioners,

v.

ZOND, LLC,  
Patent Owner.

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Case IPR2014-00799  
Patent 7,808,184 B2<sup>1</sup>

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Before JONI Y. CHANG, *Administrative Patent Judge*.

DECISION

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<sup>1</sup> This Decision addresses the same issue in the *inter partes* reviews listed in the Appendix. Therefore, we issue one Decision to be filed in all of the cases. The parties, however, are not authorized to use this style of filing in subsequent papers.

IPR2014-00799  
Patent 7,808,184 B2

Motions to Expunge  
37 C.F.R. § 42.7

Patent Owner Zond, LLC (“Zond”) filed a Motion to Expunge (Paper 25<sup>2</sup>) draft versions of Motions for *Pro Hac Vice* Admission and supporting evidence (Papers 19–22) in each of the proceedings identified in the Appendix. The Motions to Expunge are unopposed. Paper 25, 2.

Zond subsequently filed the final versions of the Motions for *Pro Hac Vice* Admission (Papers 23, 24) and supporting evidence (Exs. 2005, 2006), which will be decided in due course. For clarity of the record, Zond’s Motions to Expunge the draft versions are hereby *granted*.

Accordingly, it is

ORDERED that the following papers will be expunged upon the entry of the instant Decision: IPR2014-00477, Papers 19–22; IPR2014-00479, Papers 16–19; IPR2014-00578, Papers 18–21; IPR2014-00604, Papers 13–16; IPR2014-00799, Papers 19–22; and IPR2014-00803, Papers 18–21.

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<sup>2</sup> For the purpose of clarity and expediency, we treat IPR2014-00799 as representative, and all citations are to IPR2014-00799 unless otherwise noted.

IPR2014-00799  
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### APPENDIX

<b>U.S. Patent Numbers</b>	<b><i>Inter Partes</i> Reviews</b>
6,896,775 B2	IPR2014-00578 IPR2014-00604
7,808,184 B2	IPR2014-00799 IPR2014-00803
8,125,155 B2	IPR2014-00477 IPR2014-00479

IPR2014-00799  
Patent 7,808,184 B2

For PATENT OWNER:

Gregory J. Gonsalves  
[gonsalves@gonsalveslawfirm.com](mailto:gonsalves@gonsalveslawfirm.com)

Bruce J. Barker  
[bbarker@chsblaw.com](mailto:bbarker@chsblaw.com)

For PETITIONERS:

*TSMC and Fujitsu:*

David M O'Dell  
[david.odell.ipr@haynesboone.com](mailto:david.odell.ipr@haynesboone.com)

David L. McCombs  
[david.mccombs.ipr@haynesboone.com](mailto:david.mccombs.ipr@haynesboone.com)

Richard C. Kim  
[rckim@duanemorris.com](mailto:rckim@duanemorris.com)

Anthony J. Fitzpatrick  
[AJFitzpatrick@duanemorris.com](mailto:AJFitzpatrick@duanemorris.com)

Donald D. Jackson  
[Donald.jackson@haynesboone.com](mailto:Donald.jackson@haynesboone.com)

*Gillette:*

Michael A. Diener  
[michael.diener@wilmerhale.com](mailto:michael.diener@wilmerhale.com)

Larissa B. Park  
[larissa.park@wilmerhale.com](mailto:larissa.park@wilmerhale.com)

*GlobalFoundries:*

David Tennant  
[dtennant@whitecase.com](mailto:dtennant@whitecase.com)

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Dohm Chankong  
[dohm.chankong@whitecase.com](mailto:dohm.chankong@whitecase.com)

*AMD:*

David M. Tennant  
[dtennant@whitecase.com](mailto:dtennant@whitecase.com)

Brian M. Berliner  
[bberliner@omm.com](mailto:bberliner@omm.com)

Byan K. Yagura  
[ryagura@omm.com](mailto:ryagura@omm.com)

Xin-Yi Zhou  
[vzhou@omm.com](mailto:vzhou@omm.com)